

8 i U'B!7\ 100J': Ugh'Gk]HW]b['A C G: 9 Hg'

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- *ÁÙ*]^\ÁŠ[, ÁÕæ£^ÁÔ@æb*^Á
- ★ÁÒ¢&^||^} ơÁÔåXĐãơÁ~~^&ơÁå^&|ð;^Á
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DfcXiWhGiaaUfmÁ



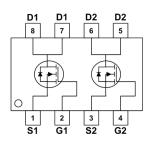
6 J 8 GG''	F8GCB"	-8 "
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8 YgW]dh]cb

\(\forall \) \(\text{\alpha} \) \(\frac{\alpha}{\alpha} \) \(\frac{\alpha}{

GCD, 'D]b'7 cb2[[i fUf]cb'





5 Vgc i MY A U]a i a 'F U b [g (T_A = 25°C, unless otherwise noted)

Parameter		Symbol	Value _Á	Unit
Drain-Source Voltage		V _{DS}	100	V
Gate-Source Voltage		V _{GS}	±20	V
Continuous Drain Current	T _A =25°C	l _D	10	A
Continuous Diam Culterit	T _A =100°C	טו	3.5	7
Pulsed Drain Current ¹		Ірм	16	А
Single Pulse Avalanche Energy ²		EAS	3.2	mJ
Total Power Dissipation	T _A =25°C	P _D	3.1	W
Operating Junction and Storage Temperat	ure Range	TJ, Á	-55 to 150	°C

Thermal Characteristics

Parameter	Symbol	Value	Unit
Thermal Resistance from Junction-to-Ambient ³	R _{0JA}	40.3	°C/W



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Electrical Characteristics (T_J = 25°C, unless otherwise noted)

Parameter		Symbol	Test Conditions	Min.	Тур.	Max.	Unit
Static Characteristics				•	•		
Drain-Source Breakdown Volta	age	V _{(BR)DSS}	V _{GS} = 0V, I _D = 250µA	100	-	-	V
Gate-Body Leakage Current		I _{GSS}	V _{DS} = 0V, V _{GS} = ±20V	-	-	±100	nA
Zero Gate Voltage Drain	T _J =25°C		\/ 400\/ \/ O\/	-	-	1	
Current	T _J =100°C	IDSS	$V_{DS} = 100V, V_{GS} = 0V$	-	-	100	μA
Gate-Threshold Voltage		V _{GS(th)}	$V_{DS} = V_{GS}$, $I_D = 250\mu A$	1	1.7	3	V
		_	V _{GS} = 10V, I _D = 4A	-	68	100	
Drain-Source on-Resistance ⁴		R _{DS(on)}	V _{GS} = 4.5V, I _D = 2A	-	78	110	mΩ
Forward Transconductance ⁴		g fs	V _{DS} =10V , I _D =4A	-	11	-	S
Dynamic Characteristics ⁵	i						
Input Capacitance		C _{iss}		-	1233	-	
Output Capacitance		Coss	V _{DS} = 50V, V _{GS} =0V, f =1MHz	-	32	-	pF
Reverse Transfer Capacitance		C _{rss}		-	26	ı	
Gate Resistance		Rg	f =1MHz	-	1.4	-	Ω
Switching Characteristics	5						
Total Gate Charge		\mathbf{Q}_{g}		-	12	-	nC
Gate-Source Charge		\mathbf{Q}_{gs}	$V_{GS} = 10V, V_{DS} = 50V,$ $I_{D}=4A$	-	2.9	ı	
Gate-Drain Charge		\mathbf{Q}_{gd}		-	1.8	-	
Turn-on Delay Time		t _{d(on)}		-	3.9	-	
Rise Time		tr	V _{GS} =10V, V _{DD} =50V,	-	26	-	no
Turn-off Delay Time		t _{d(off)}	$R_G = 3\Omega$, $I_D = 4A$	-	16.2	-	ns
Fall Time		t _f		-	8.9	-	
Body Diode Reverse Recovery Time		t _{rr}		-	40	-	ns
Body Diode Reverse Recovery	y Charge	Qrr	- I _F = 4A, dI/dt=100A/μs	-	43	-	nC
Drain-Source Body Diode	Character	istics	•	•	•		
Diode Forward Voltage ⁴		V _{SD}	Is = 1A, V _{GS} = 0V	-	-	1.2	V
Continuous Source Current	T _A =25°C	Is	-	-	-	10	Α

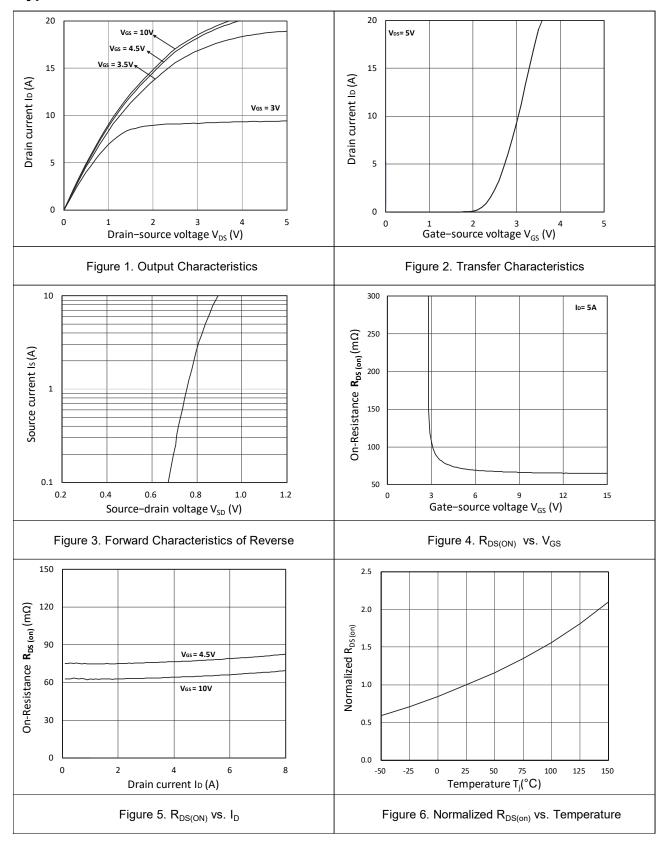
Notes:

- 1. Repetitive rating, pulse width limited by junction temperature $T_{J(MAX)}$ =150°C.
- 2. The EAS data shows Max. rating . The test condition is V_{DD} =25V, V_{GS} =10V, L=0.1mH, I_{AS} =8A .
- 3. The data tested by surface mounted on a 1 inch2 FR-4 board with 2OZ copper, The value in any given application depends on the user's specific board design.
- 4. The data tested by pulsed , pulse width \leq 300us , duty cycle \leq 2%.
- 5. This value is guaranteed by design hence it is not included in the production test..



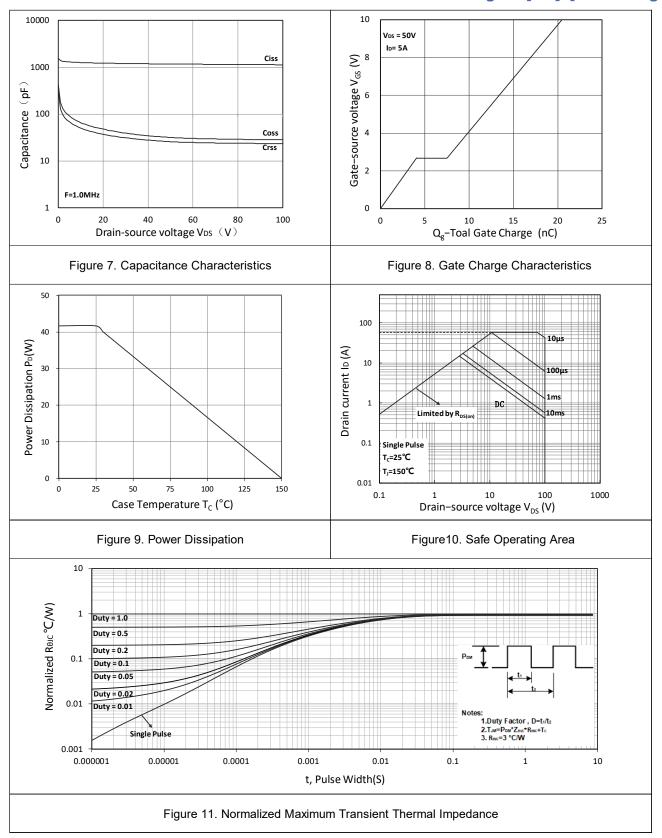
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Typical Characteristics





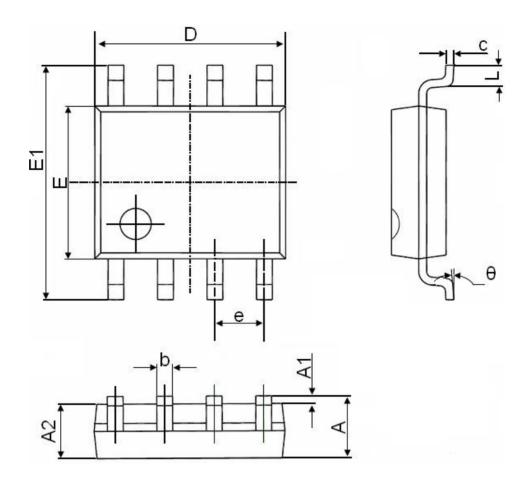
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SOP-8 Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches		
	Min.	Max.	Min.	Max.	
Α	1.350	1.750	0.053	0.069	
A1	0.100	0.250	0.004	0.010	
A2	1.350	1.550	0.053	0.061	
b	0.330	0.510	0.013	0.020	
С	0.170	0.250	0.006	0.010	
D	4.700	5.100	0.185	0.200	
E	3.800	4.000	0.150	0.157	
E1	5.800	6.200	0.228	0.244	
е	1.270(BSC)		0.050	(BSC)	
L	0.400	1.270	0.016	0.050	
θ	0°	8°	0°	8°	